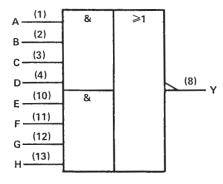
- Package Options Include "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain 2-wide 4-input AND-OR-INVERT gates. They perform the Boolean function $Y = \overline{ABCD + EFGH}$.

The SN54LS55 is characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 $^{\circ}\text{C}$. The SN74LS55 is characterized for operation from 0 $^{\circ}\text{C}$ to 70 $^{\circ}\text{C}$.

logic symbol†

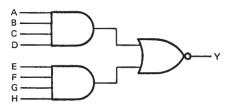


positive logic: $Y = \overline{ABCD + EFGH}$

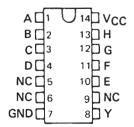
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

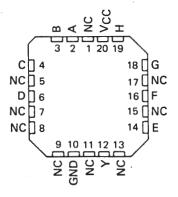
logic diagram



SN54LS55 . . . J OR W PACKAGE SN74LS55 . . . D OR N PACKAGE (TOP VIEW)

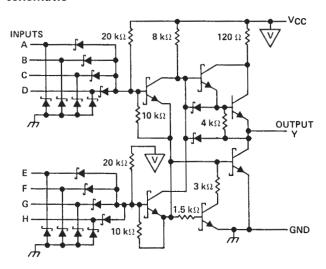


SN54LS55 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

schematic



Resistor values shown are nominal.

SDLS181 - DECEMBER 1983 - REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note	; 1)	7 V
Input voltage	***************************************	
Operating free-air temperature:	SN54LS55	-55°C to 125°C
	SN74LS55	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		S	SN54LS55			SN74LS55		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ГОН	High-level output current			- 0.4			- 0.4	mA
loL	Low-level output current			4			. 8	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS55	SN74LS55	UNIT
	TEST CONDITIONS!	MIN TYP# MAX	MIN TYP\$ MAX	
v_{iK}	$V_{CC} = MIN$, $I_1 = -18 \text{ mA}$	- 1.5	1.5	V
Voн	$V_{CC} = MIN$, $V_{IL} = MAX$, $I_{OH} = -0.4 \text{ mA}$	2.5 3.4	2.7 3.4	V
VOL	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 4 mA	0.25 0.4	0.25 0.4	v
	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 8 mA		0.35 0.5	
l _l	V _{CC} = MAX, V _I = 7 V	0.1	0.1	mA
Чн	VCC = MAX, VI = 2.7 V	20	20	μА
HL	VCC = MAX, VI = 0.4 V	0.4	- 0.4	mA
los§	VCC = MAX	- 20 - 100	- 20 - 100	mA
Іссн	VCC = MAX, VI = 0 V	0.4 0.8	0.4 0.8	mA
ICCL	VCC = MAX, See Note 2	0.7 1.3	0.7 1.3	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
^t PLH	Any	Y	$R_1 = 2 k\Omega$, C	ı = 15 pF		12	20	ns
^t PHL	,,			[10 bi		12.5	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ} \text{C}$.

[§]Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTE 2: All outputs of one AND gate at 4.5 V, all others at GND.

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1999, Texas Instruments Incorporated